

AMENDMENTS TO THE CLAIMS

1-5. (Cancelled)

6. (Previously Presented) A method for manufacturing a plasma display panel (PDP) including a process for forming a metal oxide film onto a substrate of the PDP, the method comprising:

introducing inert gas into a deposition room during deposition of the metal oxide film;
introducing oxygen into the deposition room during deposition of the metal oxide film;
introducing at least one gas selected from the group consisting of carbon monoxide and carbon dioxide into the deposition room during deposition of the metal oxide film, wherein the oxygen and the at least one gas are introduced into the deposition room in a predetermined amount;
controlling an amount of dangling bonds in the metal oxide film; and
equilibrating the amounts of the gasses introduced into the deposition room with an amount of gas exhausted from the deposition room by a vacuum exhausting system so as to maintain a degree of vacuum in the deposition room within a range of 1×10^{-1} Pa to 1×10^{-2} Pa, wherein said equilibrating of the amounts comprises adjusting an amount of the inert gas introduced into the deposition room,

wherein the oxygen gas is introduced into the deposition room so as to restrain the amount of dangling bonds in the metal oxide film, and wherein the at least one gas is introduced into the deposition room so as to increase the amount of dangling bonds in the metal oxide film.

7. (Previously Presented) The method for manufacturing the PDP of claim 6, wherein said introducing of the at least one gas comprises introducing at least one gas selected from the group consisting of carbon monoxide and carbon dioxide at a constant amount into the deposition room, and

wherein said controlling of the amount of dangling bonds comprises adjusting an amount of the oxygen gas introduced into the deposition room.

8. (Previously Presented) The method for manufacturing the PDP of claim 6, wherein said introducing of oxygen comprises introducing an amount of oxygen at a constant value, and

wherein said controlling of the amount of dangling bonds comprises adjusting an amount of the at least one gas selected from the group consisting of carbon monoxide and carbon dioxide introduced into the deposition room.

9-10. (Cancelled)